Amendments to the Specification

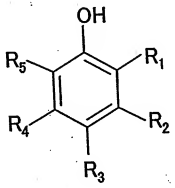
On page 1, please delete the paragraph beginning in line 4 and insert:

This application is a continuation-in-part of our copending U.S. patent application no. 10/797,706 filed March 10,2004, which is now U.S. Patent 7,023,098 and is based on Japanese patent application No. 2003-083637 and Japanese patent application No. 2003-083938, the content of which is incorporated hereinto by reference.

On page 13, please replace the paragraph beginning on line 4 and continuing on page 14, lines 1 and 2, with the following:

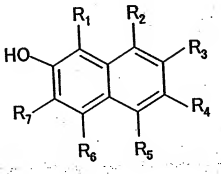
Compound (F) containing two and more hydroxyl groups combined with each of adjacent carbon atoms comprising an aromatic ring may contain optionally a substituent other than the hydroxyl groups.

Compound (F) may be a monocyclic compound represented by general formula (5):



(5)

wherein one of R_1 and R_5 is hydroxyl and the other is hydrogen, hydroxyl or a substituent other than hydroxyl; and R_2, R_3 and R_4 are hydrogen, hydroxyl or a substituent other than hydroxyl; or a polyclic compound represented by general formula (6):



(6)

wherein one of R_1 and R_7 is hydroxyl and the other is hydrogen, hydroxyl or a substituent other than ~~hydrox~~ hydroxyl; and R_2, R_3, R_4, R_5 and R_6 are hydrogen, hydroxyl or a substituent other than hydroxyl.

On page 16, please replace the paragraph beginning with "Example 1" (line 26 to page 17, line 17) with the following:

Example 1

A phenol biphenylaralkyl type epoxy resin (Nippon Kayaku Co., Ltd., NC3000-P, epoxy equivalent: 274, "n" in formula (1) is 2.8 as an average, softening point: 58 °C): 7.35 wt parts;

phenol biphenylaralkyl resin (Meiwa Kasei Co., Ltd., MEH-7851SS, hydroxyl equivalent 203, "n" in formula (2) is 2.5 as an average, softening point: 65 °C): 5.5 wt parts;

spherical fused silica (average particle size: 30 μm): 86.0 wt parts;

~~γ-glycidylpropyl-trimethoxysilane~~ γ-glycidoxypropyl-trimethoxysilane: 0.4 wt parts;

triphenyl phosphine: 0.2 wt parts;

2,3-dihydroxynaphthalene (Reagent grade): 0.05 wt parts;

carnauba wax: 0.2 wt parts; and

carbon black: 0.3 wt parts

were mixed in a mixer at an ambient temperature, followed by melt kneading by a heating roller at 80 to 100 °C, cooling and then grinding to obtain an epoxy resin composition. The resultant epoxy resin composition was evaluated as follows. The evaluation results are shown in Table 1.

Please replace Table 1 on page 21 with the following table:

TABLE 1

		Example												
		1	2	3	4	5	6	7	8	9	10	11	12	13
Phenol biphenylaralkyl type epoxy resin		7.35	4.0	8.65	7.5	7.13	7.42	7.35	7.35	7.35	7.35	7.35	7.35	7.35
Biphenyl type epoxy resin			1.0											
Phenol biphenylaralkyl resin		5.5	2.5	5.5	5.5	5.3	5.5	5.5	5.5	5.5	5.5	5.5	5.45	5.45
Phenolaralkyl resin			1.3											
Spherical fused silica		86.0	90.0	84.5	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0
γ-Glycidoxypropyltrimethoxysilane		0.4	0.5	0.3	0.05	0.85	0.03	0.4	0.4	0.4		0.4	0.4	0.4
γ-Mercaptopropyltrimethoxysilane											0.4			
Triphenylphosphine		0.2	0.13	0.25	0.2	0.2	0.2	0.2	0.2	0.2	0.2			
DBU												0.2		
Curing accelerator of formula (7)													0.25	
Curing accelerator of formula (8)														0.25
2,3-Dihydroxynaphthalene		0.05	0.07	0.1	0.25	0.02	0.35				0.05	0.05	0.05	0.05
1,2-Dihydroxynaphthalene								0.05						
Catechol									0.05					
Pyrogallol										0.05				
1,6-Dihydroxynaphthalene														
Resorcinol														
Carnauba wax		0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2
Carbon black		0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3
Spiral flow	(cm)	100	85	121	115	96	118	104	89	113	106	102	112	105
Curing torque ratio	(%)	65	61	66	60	68	58	63	64	61	63	61	85	89
Solder resistance-cracking	Chip delamination	0	0	0	0	0	0	0	0	0	0	0	0	0
	Internal crack	0	0	0	0	0	0	0	0	0	0	0	0	0
Fire retardancy		V-0	V-0	V-0	V-0	V-0	V-0	V-0	V-0	V-0	V-0	V-0	V-0	V-0

Please replace Table 2 on page 22 with the following table:

TABLE 2

		Comparative Example														
		1	2	3	4	5'	6	7	8	9	10	11	12	13	14	15
Phenol bisformylvinylalkyl type epoxy resin		7.4	3.6	8.5	8.4		7.4	7.1	7.5	7.412	7.5	7.55	7.55	7.4	7.35	7.35
Bisformyl type epoxy resin			0.9													
Cresol novolac type epoxy resin						6.9		5.5	5.65	5.52	5.48	5.65	5.5	5.5	5.5	5.5
Phenol bisformylvinylalkyl resin		5.5	6.9	6.35												
Phenolvinylalkyl resin			1.0			6.0										
Phenol novolac resin					3.5											
Spherical fused silica		86.0	81.0	83.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0
7-(Glycidoxypropyl)trimethoxysilane		0.4	0.5	0.3	0.4	0.4		0.4	0.4	0.4		0.4	0.4	0.4	0.4	0.4
7-Mercaptopropyltrimethoxysilane							0.4									
DBU		0.2	0.13	0.25	0.15	0.15	0.2	0.2	0.08	0.2	0.2	0.2	0.2	0.2		
Triphenylphosphine															0.05	
Curing accelerator of formula (7)																0.05
Curing accelerator of formula (8)																
2,2-Dihydroxynaphthalene			0.07	0.1	0.05	0.05		0.035		0.036	0.05					
1,2-Dihydroxynaphthalene																
Cresol																
Pyrogallol																
1,6-Dihydroxynaphthalene												0.05				
Resorcinol													0.05			
Carnauba wax		0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2
Carbon black		0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3
Silane fiber	(ppm)	80	83	126	78	71	82	118	114	81	76	78	81	80	89	77
Silica/resin mass ratio	(%)	65	62	65	67	70	62	22	7	65	56	65	64	57	65	69
Solder resistance-cracking	Chip delamination	4	chip	0	2	chip	3	Poor		1	0	0	5	4	2	0
	Internal crack	0	exposure	2	10	exposure	0	releasing	releasing	0	0	0	0	0	0	0
Fire retardancy		V-0	V-0	V-1	V-1	HB	V-0			V-0	V-0	V-0	V-0	V-0	V-0	V-0